

Purolite™ A510MBOHPlus

聚苯乙烯 大孔, II型强碱阴树脂, 氢氧型, 混床级别

主要应用

- 脱盐 - 工业
- 混床 阴离子组分

产品优势

- 高再生效率

适用系统

- 混床脱盐
- 工作混床

包装样式

- 1 CF 编织袋
- 25L 阀口袋
- 5 CF 纤维板桶

典型物理和化学参数

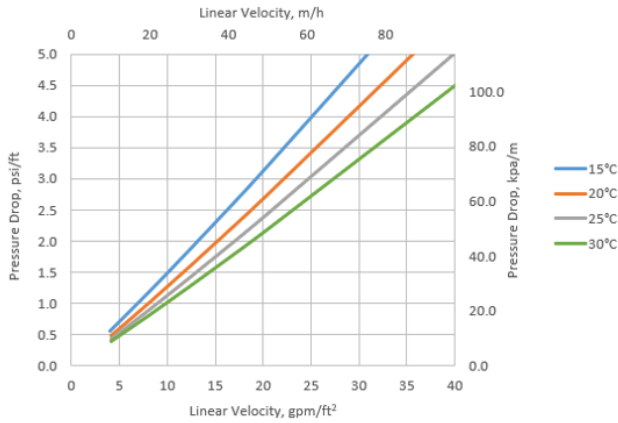
聚合物骨架	大孔型聚苯乙烯二乙烯苯交联
外观	球状颗粒
官能团	季铵II型
离子形态	OH- 型
全交换容量 (最小)	1.1 eq/L (24.0 Kgr/ft ³) (Cl ⁻ 型)
含水量	50 - 60 % (Cl ⁻ 型)
粒径分布	300 - 1200 μm
< 300 μm (最大)	1 %
均一系数 (最大)	1.7
转型膨胀率, Cl ⁻ → OH ⁻ (最大)	15 %
比重	1.07
包装密度 (大约)	675 - 705 g/L (42.2 - 44.1 lb/ft ³)
温度限制	100 °C (212.0 °F) (Cl ⁻ 型)
温度限制	35 °C (95.0 °F) (OH- 型)

水力学特性

压降

离子交换树脂的压降取决于粒度分布、床层高度、树脂颗粒间空隙体积，以及物料的流速和粘度。任何对这些参数的影响-比如被树脂床层截住的颗粒物、对树脂床层的异常压缩、床层的不规则分布-都会对压降产生不利影响，造成压头损失。针对不同的物料质量、应用环境和系统设计，流速可能处于10 – 40 BV/h范围内变化。

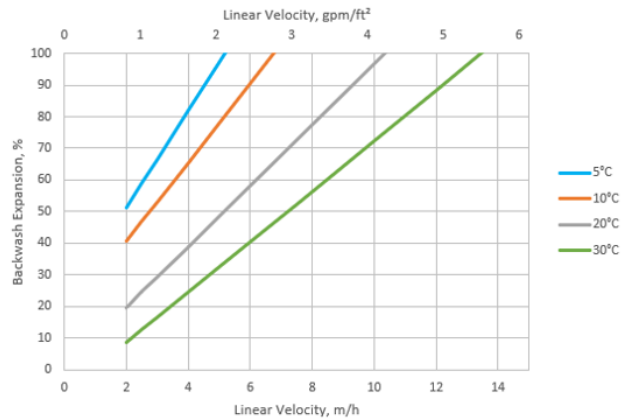
床层压降



反洗

在自下而上反洗过程中，应控制反洗膨胀率在50%到70%之间，至少保持10到15分钟。该操作除去（运行过程中截留的物料中的）颗粒物，清除气泡，并重新规整树脂颗粒，确保最小的流动阻力。第一次投入前，大约30分钟的充分反洗，通常就足以对树脂床层进行适当的规整。值得注意的是，相同流速下反洗膨胀率随温度降低而升高。必须注意，应避免将树脂床层反洗膨胀过甚而导致树脂从顶部流失。

树脂床反洗膨胀率



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